The reference design PMP10215 Rev-D has been built on PMP10215 Rev-B Board

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE
M1 Board Outline

M1 Board Outline

TID #: .TID

PLOT NAME = Assembly Top
GENERATED : 4/26/2016 10:38:36 AM
TEXAS INSTRUMENTS
The reference design PMP10215 Rev-D has been built on PMP10215 Rev-B Board

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

<table>
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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP10215</th>
<th>REV; B</th>
<th>SUN REV: Not In VersionControl</th>
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<tr>
<td>TID #: .TID</td>
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<tr>
<td>PLOT NAME = Assembly Bottom</td>
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